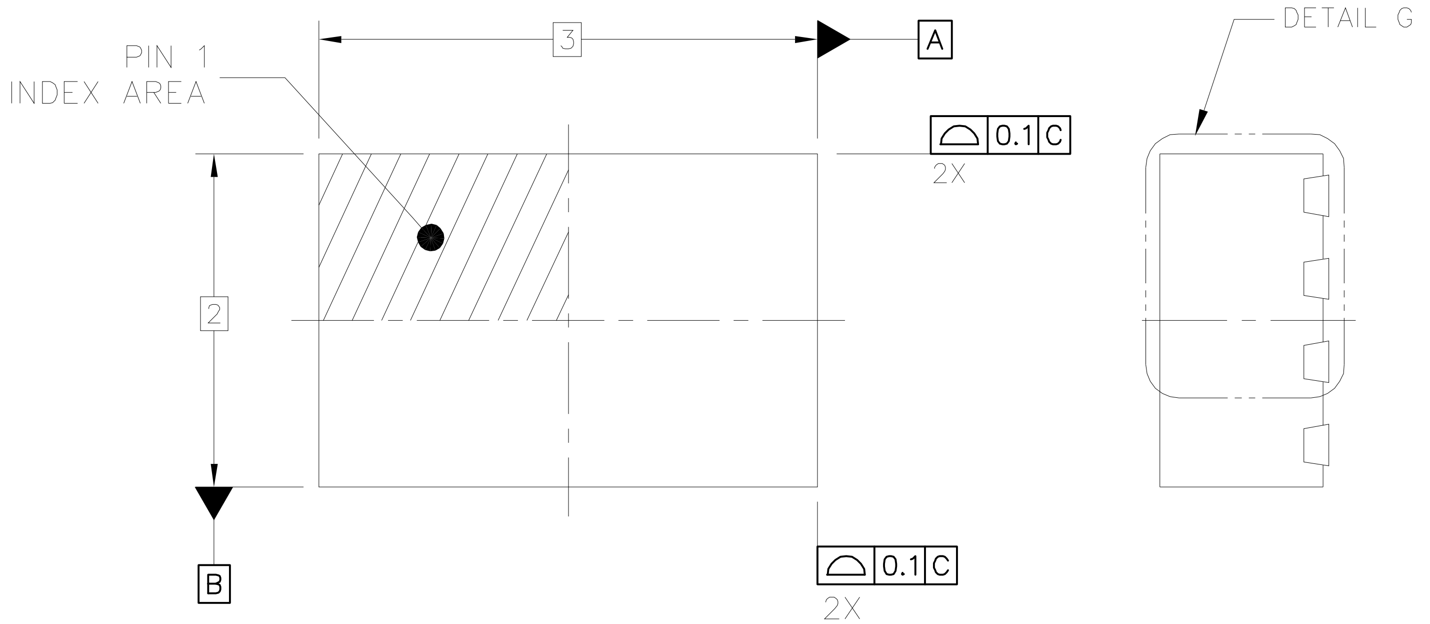

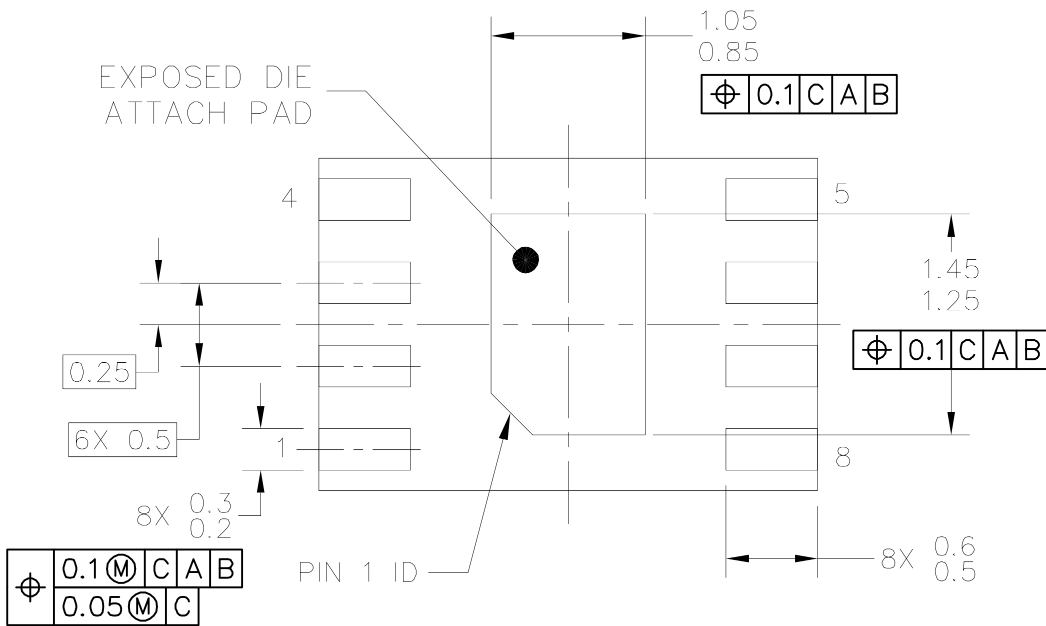

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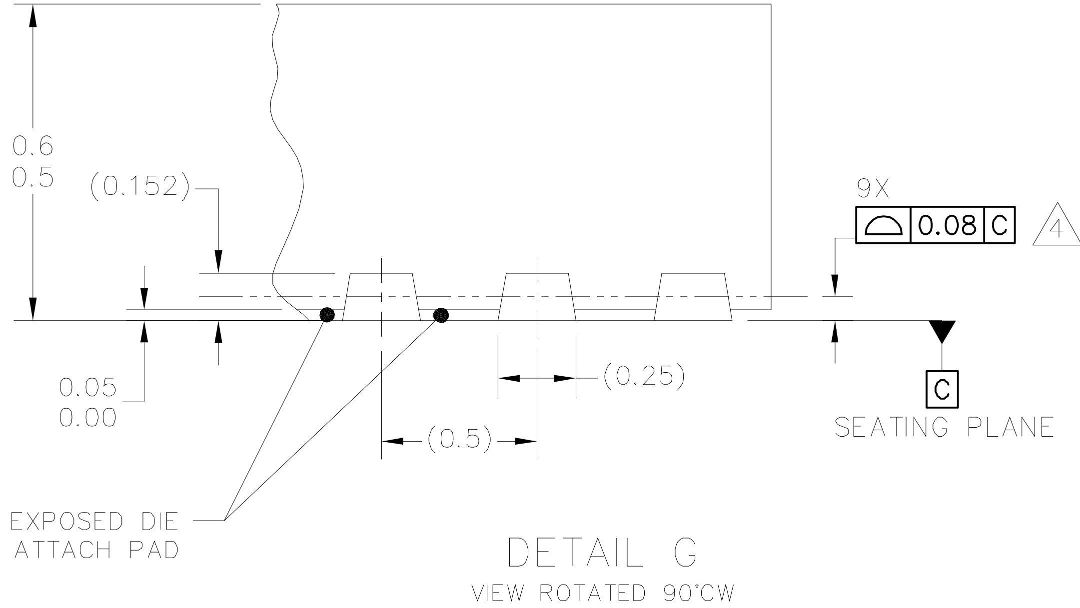
MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED PLASTIC ULTRA THIN DUAL FLAT NO LEAD PACKAGE 8 TERMINAL, 0.5 PITCH (3 X 2 X 0.55)	DOCUMENT NO: 98ASA01044D REV: O
	STANDARD: NON-JEDEC
	SOT1590-2 10 JAN 2017



DETAIL G

VIEW ROTATED 90°CW

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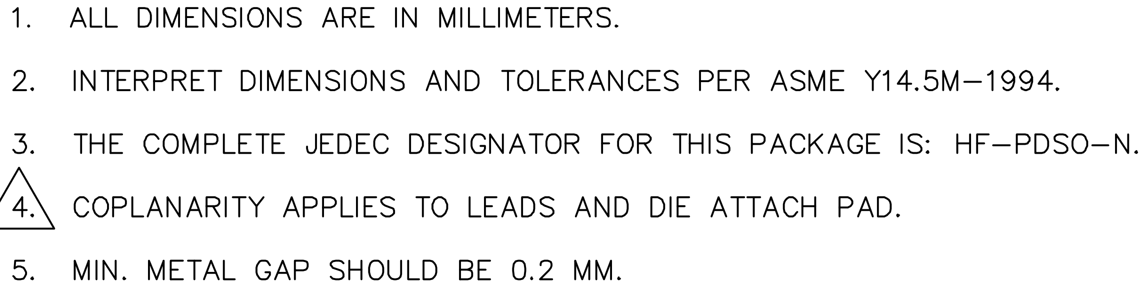
MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED PLASTIC ULTRA THIN DUAL FLAT NO LEAD PACKAGE 8 TERMINAL, 0.5 PITCH (3 X 2 X 0.55)	DOCUMENT NO: 98ASA01044D REV: 0
	STANDARD: NON-JEDEC
	SOT1590-2 10 JAN 2017



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PDSO-N.

4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.

5. MIN. METAL GAP SHOULD BE 0.2 MM.

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